

1. A method for connecting a first and a second conductive surface, comprising the steps of:

placing an anisotropic material between the first and second conductive surfaces to form an assembly;

curing the anisotropic material;

compressing the assembly to form a bond between the first and second conductive surfaces via the anisotropic material; and

monitoring an electrical characteristic of the bond during at least one of the compressing and curing steps and generating a feedback signal corresponding to the electrical characteristic.

2. The method of claim 1, further comprising the step of adjusting an amount of pressure applied during the compressing step in response to the feedback signal.

7. The method of claim 6, wherein the curing step includes maintaining the anisotropic material at an approximately constant elevated temperature.

9. A system for connecting a first and second conductive surface, comprising:

a compressor that applies pressure to an assembly having a first conductive surface and a second conductive surface with an anisotropic material disposed between